

SOT782-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

14 June 2016

Package information

1. Package summary

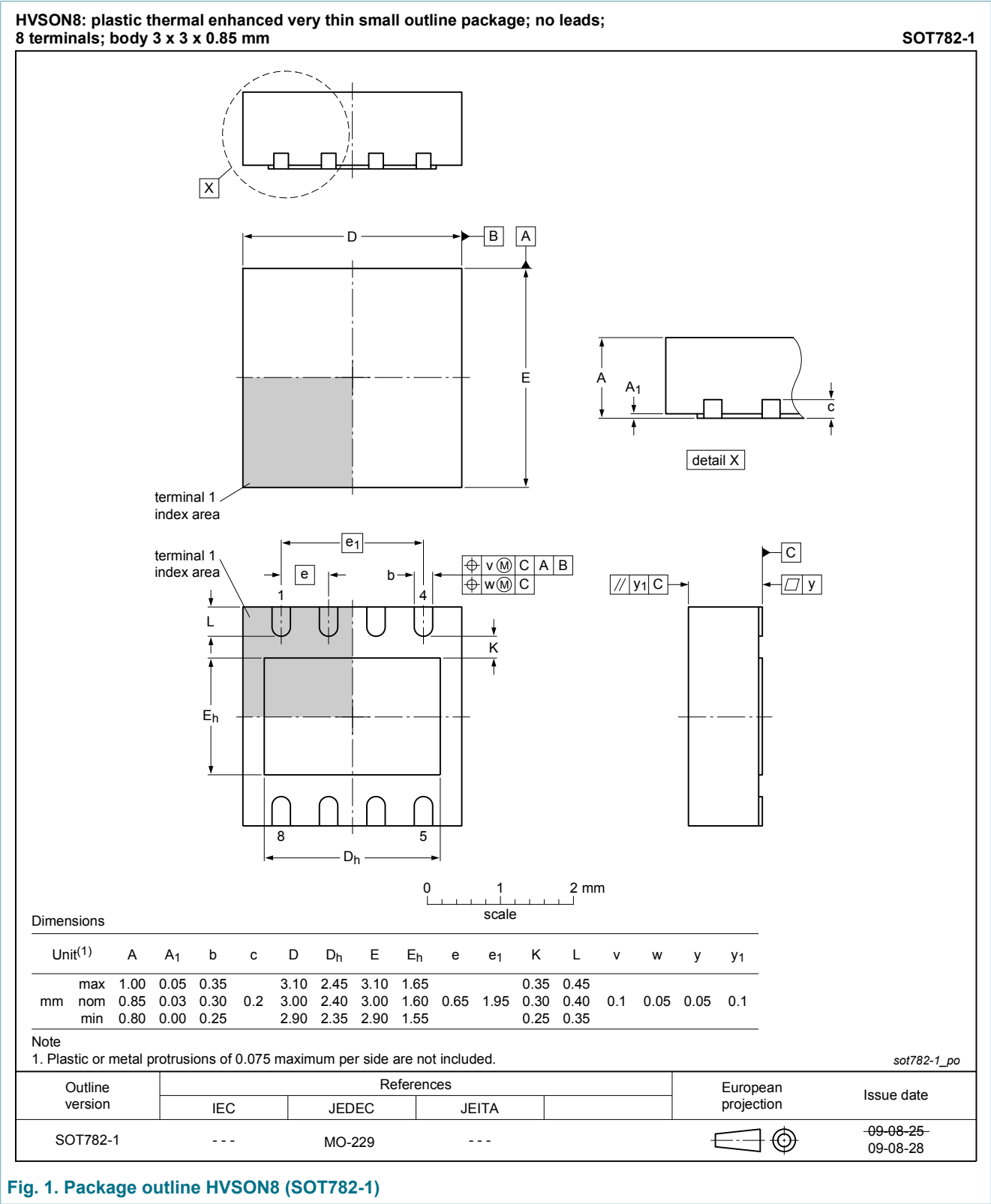
Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	MO-229
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	28-8-2009

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.9	-	3	3.1	mm
E	package width		2.9	-	3	3.1	mm
A	seated height		0.8	-	0.85	1	mm
A ₂	package height		-	-	0.82	-	mm
e	nominal pitch		-	-	0.65	-	mm
n ₂	actual quantity of termination		-	-	8	-	



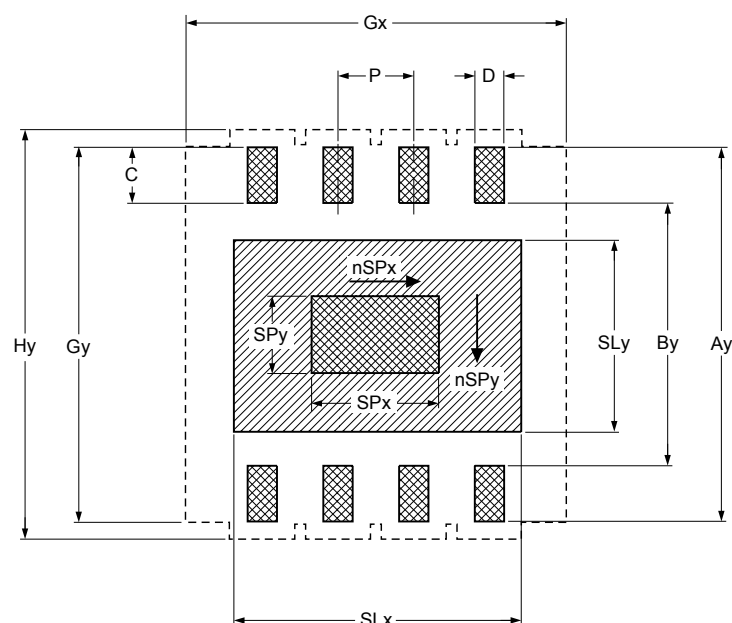
2. Package outline






3. Soldering

Footprint information for reflow soldering of HVSON8 package

SOT782-1



-  solder land
 solder paste deposit
 solder land plus solder paste
 - - - - occupied area

DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	Gy	Hy
0.65	3.25	2.2	0.525	0.3	2.45	1.65	1.1	0.65	3.25	3.25	3.5

Issue date	12-02-09 12-02-28
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nSPx	nSPy
1	1

sot782-1 fr

Fig. 2. Reflow soldering footprint for HVSON8 (SOT782-1)

4. Legal information

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